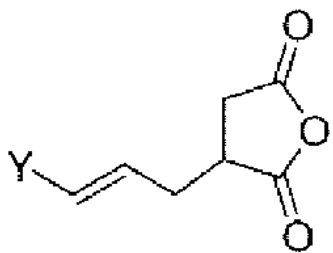


ABSTRACT

The present invention provides a compound having excellent heat resistance and low dielectric properties, and a curable resin composition and a cured product thereof. The compound is obtained by reacting a compound represented by formula (a) with a compound
5 having two or more amino groups per molecule. (In formula (a), Y represents a C1-20 hydrocarbon group.)



(a)

[No suitable accompanying drawing]